

L Number	Hits	Search Text	DB	Time stamp
1	994	waveguide and cladd\$4 and anneal\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:46
2	7	(waveguide and cladd\$4 and anneal\$4) and (high\$1density adj plasma\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:49
3	15	(high\$1density adj plasma\$4) and (cladd\$4 OR gap adj fill) and waveguide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:49
4	1822	((65/386,413,398,391) or (385/129)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 18:08
5	11	((65/386,413,398,391) or (385/129)).CCLS.) and (high\$1density adj plasma OR HDP)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 18:09
-	4789	waveguide and cladd\$4 and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:45
-	4099	waveguide and cladding and etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:05
-	939	(waveguide and cladd\$4 and etch\$4) and sputter\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:06
-	72	((waveguide and cladd\$4 and etch\$4) and sputter\$4) and planar adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:06
-	1893	((65/386) or (385/129,132)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 13:05
-	0	("6andcladd\$4").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:32
-	649	((65/386) or (385/129,132)).CCLS.) and cladd\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:32
-	12	((65/386) or (385/129,132)).CCLS.	USOCR	2003/09/04 13:06
-	13	(65/391,413,429,436).CCLS.	USOCR	2003/09/04 13:07

-	551	(65/391,413,429,436).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 13:07
-	194	((65/391,413,429,436).CCLS.) and cladd\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 13:08
-	4789	waveguide and cladd\$4 and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 17:20
-	143	(waveguide and cladd\$4 and etch\$4) and shadow\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 17:30
-	2	("6506289").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 17:30
-	22	("4437966" "5107538" "5119460" "5206925" "5252194" "5303319" "5381262" "5475528" "5483613" "5555127" "5563979" "5565071" "5603816" "5613995" "5719976" "5831262" "5841931" "5847865" "5855744" "5900057" "5966491" "6157765").PN.	USPAT	2003/09/04 17:30
-	0	6506289.URPN.	USPAT	2003/09/04 17:33

L Number	Hits	Search Text	DB	Time stamp
1	994	waveguide and cladd\$4 and anneal\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:46
2	7	(waveguide and cladd\$4 and anneal\$4) and (high\$1density adj plasma\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:49
3	15	(high\$1density adj plasma\$4) and (cladd\$4 OR gap adj fill) and waveguide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:49
4	1822	((65/386,413,398,391) or (385/129)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 18:08
5	11	((65/386,413,398,391) or (385/129)).CCLS.) and (high\$1density adj plasma OR HDP)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 18:09
-	4789	waveguide and cladd\$4 and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/07 17:45
-	4099	waveguide and cladding and etching	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:05
-	939	(waveguide and cladd\$4 and etch\$4) and sputter\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:06
-	72	((waveguide and cladd\$4 and etch\$4) and sputter\$4) and planar adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:06
-	1893	((65/386) or (385/129,132)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 13:05
-	0	("6andcladd\$4").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:32
-	649	((65/386) or (385/129,132)).CCLS.) and cladd\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 12:32
-	12	((65/386) or (385/129,132)).CCLS.	USOCR	2003/09/04 13:06
-	13	(65/391,413,429,436).CCLS.	USOCR	2003/09/04 13:07

-	551	(65/391,413,429,436).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 13:07
-	194	((65/391,413,429,436).CCLS.) and cladd\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 13:08
-	4789	waveguide and cladd\$4 and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 17:20
-	143	(waveguide and cladd\$4 and etch\$4) and shadow\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 17:30
-	2	("6506289").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 17:30
-	22	("4437966" "5107538" "5119460" "5206925" "5252194" "5303319" "5381262" "5475528" "5483613" "5555127" "5563979" "5565071" "5603816" "5613995" "5719976" "5831262" "5841931" "5847865" "5855744" "5900057" "5966491" "6157765").PN.	USPAT	2003/09/04 17:30
-	0	6506289.URPN.	USPAT	2003/09/04 17:33